



Material Content Data Sheet



Sales Product Name	BTS3205G			Issued		27. February 2015		
MA#	MA001052994							
Package	PG-DSO-8-24			Weight*		82.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.717	0.87	0.87	8657	8657
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8660	
	non noble metal	copper	7440-50-8	29.121	35.16	36.08	351640	360841
wire	noble metal	gold	7440-57-5	0.236	0.28	0.28	2846	2846
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1211	
	plastics	epoxy resin	-	4.612	5.57		55696	
	inorganic material	silicondioxide	60676-86-0	45.423	54.85	60.54	548482	605389
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9827	9827
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7852	7852
glue	plastics	epoxy resin	-	0.066	0.08		803	
	noble metal	silver	7440-22-4	0.313	0.38	0.46	3785	4588
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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